

3.2x1.6mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Part Number: KP-3216LSURCK

HYPER RED

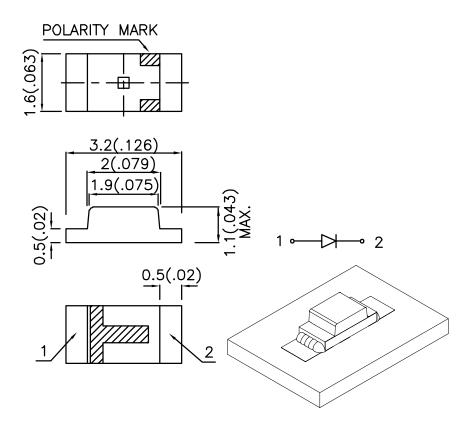
Features

- •3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS/REEL.
- •LOW CURRENT IF=2mA OPERATING.
- •MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- •RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2 (0.008\mbox{"})$ unless otherwise noted.
- Specifications are subject to change without notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.





SPEC NO: DSAB7510 **REV NO: V.3** DATE: MAY/09/2007 **PAGE: 1 OF 4** APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: W.J.HUA

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Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Тур.	201/2
KP-3216LSURCK	HYPER RED (InGaAIP)	WATER CLEAR	3	15	120°

Notes:

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=2mA
λD [1]	Dominate Wavelength	Hyper Red	635		nm	IF=2mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=2mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
V _F [2]	Forward Voltage	Hyper Red	1.75	2.5	V	IF=2mA
lr	Reverse Current	Hyper Red		10	uA	VR = 5V

- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at Ta=25°C

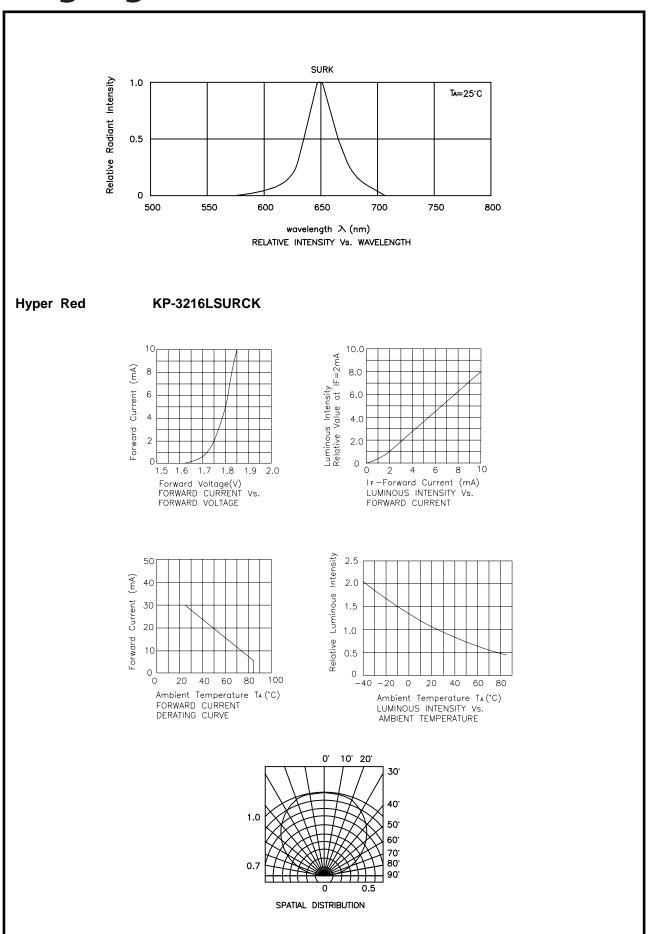
Parameter	Hyper Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	185	mA	
Reverse Voltage	5	V	
Operating / storage Temperature	-40°C To +85°C		

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

SPEC NO: DSAB7510 **REV NO: V.3** DATE: MAY/09/2007 PAGE: 2 OF 4 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: W.J.HUA

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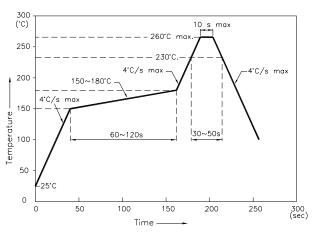


SPEC NO: DSAB7510 REV NO: V.3 DATE: MAY/09/2007 PAGE: 3 OF 4
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: W.J.HUA

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Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

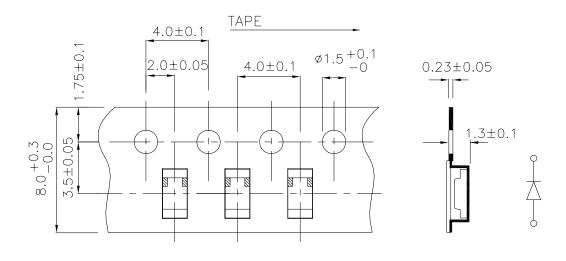
- 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

1.75 2.0 1.75

Tape Specifications (Units: mm)



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